L Number	Hits	Search Text	DB	Time stamp
-	9844	((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$4)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:15
-	10015	((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$45)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 07:54
-	7329	((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$45)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 07:57
-	10011	((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$5)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 07:57
-	733	(((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$5)).clm.) and capacit$5.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 07:57
-	264	((((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$5)).clm.) and capacit$5.clm.) and electrode.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 07:57
-	53	(((((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$5)).clm.) and capacit$5.clm.) and electrode.clm.) and (concentration impurity purity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:36
-	17	(((((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 (conduct$5)).clm.) and capacit$5.clm.) and electrode.clm.) and (concentration impurity purity).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:28
-	700	(216/2).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:36
-	92	((216/2).CCLS.) and impurit$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:37
-	1	(((216/2).CCLS.) and impurit$4 near3 concentration) and etch near1 pit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:39
-	1	((((216/2).CCLS.) and impurit$4 near3 concentration) and etch near1 pit) and diaphragm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:39
-	23	((216/2).CCLS.) and impurit$4 near3 concentration	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:41
-	20	(((216/2).CCLS.) and impurit$4 near3 concentration) and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:48

-	15	((((216/2).CCLS.) and impurit$4 near3 concentration) and etch) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:32
-	3	(((((216/2).CCLS.) and impurit$4 near3 concentration) and etch) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)) and etch near3 (pit hole groove dip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:26
-	3	(((216/2).CCLS.) and impurit$4 near3 concentration) and etch near3 (pit hole groove dip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:49
-	2	(((((216/2).CCLS.) and impurit$4 near3 concentration) and etch) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)) and electrode near3 dielectric near3 (film layer support substrate cover$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:57
-	1	((((((216/2).CCLS.) and impurit$4 near3 concentration) and etch) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)) and electrode near3 dielectric near3 (film layer support substrate cover$4)) and pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:55
-	1	(((((((216/2).CCLS.) and impurit$4 near3 concentration) and etch) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)) and electrode near3 dielectric near3 (film layer support substrate cover$4)) and pressure) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 18:55
-	11	(((((216/2).CCLS.) and impurit$4 near3 concentration) and etch) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)) and pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:04
-	6	(((((216/2).CCLS.) and impurit$4 near3 concentration) and etch) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)) and pressure near3 (sens$4 measur$3 detect test transducer gauge monitor evaluate estimat$4 identif$4 indicat$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:27
-	44167	impurit$4 near3 concentration	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:27
-	1092	(impurit$4 near3 concentration) and pressure near3 (sens$4 measur$3 detect test transducer gauge monitor evaluate estimat$4 identif$4 indicat$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:29
-	18	((impurit$4 near3 concentration) and pressure near3 (sens$4 measur$3 detect test transducer gauge monitor evaluate estimat$4 identif$4 indicat$4)) and etch near3 (pit groove hole dip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:30
-	13	(((impurit$4 near3 concentration) and pressure near3 (sens$4 measur$3 detect test transducer gauge monitor evaluate estimat$4 identif$4 indicat$4)) and etch near3 (pit groove hole dip)) and (diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 19:32

–	29	(diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 conduct$4 same etch$4 same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:51
–	3	(diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 conduct$4 same etch$4 same pit same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:23
–	658	(361/283.1-283.4).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:24
–	1	((361/283.1-283.4).CCLS.) and etch$4 same pit same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:35
–	0	((361/283.1-283.4).CCLS.) and etch$4 near3 (pit$4 hole$4 groove$4 recess$4 opening$$) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:36
–	0	((361/283.1-283.4).CCLS.) and etch$4 near3 (pit$4 hole$4 groove$4 recess$4 opening$4) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:38
–	919	((361/283.1-283.4).CCLS.) and 73/754.ccls. or 73/718.ccls. or 73/724.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:48
–	2	(((361/283.1-283.4).CCLS.) and 73/754.ccls. or 73/718.ccls. or 73/724.ccls.) and etch$4 near3 (pit$4 opening$4 groove$4 recess$4 hole$4) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:48
–	2	(((361/283.1-283.4).CCLS.) and 73/754.ccls. or 73/718.ccls. or 73/724.ccls.) and (etch$4 concentration impurit$4 dop$$) near3 (pit$4 opening$4 groove$4 recess$4 hole$4) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:47
–	2	(((361/283.1-283.4).CCLS.) and 73/754.ccls. or 73/718.ccls. or 73/724.ccls.) and (etch$4 concentration impurit$4 dop$4) near3 (pit$4 opening$4 groove$4 recess$4 hole$4) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:48
–	0	(((361/283.1-283.4).CCLS.) and 73/754.ccls. or 73/718.ccls. or 73/724.ccls.) and (etch$4 concentration impurit$4 dop$4) near3 (pit$4 opening$4 groove$4 recess$4 hole$4) near4 density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:47
–	1694	((361/283.1-283.4).CCLS.) or 73/754.ccls. or 73/718.ccls. or 73/724.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:48
–	4	(((361/283.1-283.4).CCLS.) or 73/754.ccls. or 73/718.ccls. or 73/724.ccls.) and etch$4 near3 (pit$4 opening$4 groove$4 recess$4 hole$4) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:48
–	4	(((361/283.1-283.4).CCLS.) or 73/754.ccls. or 73/718.ccls. or 73/724.ccls.) and (etch$4 concentration impurit$4 dop$4) near3 (pit$4 opening$4 groove$4 recess$4 hole$4) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:49

–	261	(diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 conduct$4 same etch$4 same (pit$4 hole$4 groove$4 recess$4 opening$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:52
–	8	(((361/283.1-283.4).CCLS.) and 73/754.ccls. or 73/718.ccls. or 73/724.ccls.) and ((diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 conduct$4 same etch$4 same (pit$4 hole$4 groove$4 recess$4 opening$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:52
–	12	(diaphragm membrane elastic$5 flexible deformable elastom$5 resilient$5) near2 conduct$4 same etch$4 same (pit$4 hole$4 groove$4 recess$4 opening$4) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 10:53